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Nomenclature, Symbols, Units and their Usage in Spectrochemical Analysis

CUMULATIVE INDEX OF TERMS: PARTS I–XIII

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Part II. Data Interpretation [*Pure Appl. Chem.*, **45**, 99–103 (1976)].

Part III. Analytical Flame Spectroscopy and Associated Non-Flame Procedures [*Pure Appl. Chem.*, **45**, 105–123 (1976)].

Part IV. X-ray Emission Spectroscopy [*Pure Appl. Chem.*, **52**, 2541–2552 (1980)].

Part V. Radiation Sources [*Pure Appl. Chem.*, **57**, 1453–1490 (1985)].

Part VI. Molecular Luminescence Spectroscopy [*Pure Appl. Chem.*, **56**, 231–345 (1984)].

Part VII. Molecular Absorption Spectroscopy, Ultraviolet and Visible (UV/VIS) [*Pure Appl. Chem.*, **60**, 1449–1460 (1988)].

Part VIII. Nomenclature System for X-ray Spectroscopy [*Pure Appl. Chem.*, **63**, 735–746 (1991)].

Part IX. Instrumentation for the Spectral Dispersion and Isolation of Optical Radiation [*Pure Appl. Chem.*, **67**, 1725–1744 (1995)].

Part X. Preparation of Materials for Analytical Atomic Spectroscopy and other Related Techniques [*Pure Appl. Chem.*, **60**, 1461–1472 (1988)].

Part XI. Radiation Detectors [*Pure Appl. Chem.*, **67**, 1745–1760 (1995)].

Part XII. Terms Related to Electrothermal Atomization [*Pure Appl. Chem.*, **64**, 253–259 (1992)].

Part XIII. Terms Related to Chemical Vapour Generation [*Pure Appl. Chem.*, **64**, 261–264 (1992)].

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Nomenclature, symbols, units and their usage in spectrochemical analysis: Cumulative index of terms: Parts I–XIII

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Roman numeral = Part
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